# **Agilent HDMP-2634** 2.5/1.25 GBd Serdes Circuit Data Sheet

# **Description**

This data sheet describes the HDMP-2634 Serdes device for 2.5 GBd serial data rates.

The HDMP-2634 Serdes is a silicon bipolar integrated circuit in a metallized QFP package. It provides a low-cost physical layer solution for 2.5 GBd serial link interfaces including a complete Serialize/Deserialize (Serdes) function with transmit and receive sections in a single device. The HDMP-2634 is also capable of operating on 1.25 GBd serial links. Input pins TX RATE and RX RATE select the data rates on the transmit and receive sides, respectively.

As shown in Figure 1, the transmitter section accepts 10-bit wide parallel SSTL 2 data (TX[0:9]) and a 125 MHz SSTL\_2 byte clock (TBC) and serializes them into a highspeed serial stream. The parallel data is expected to be "8B/10B" encoded data or equivalent. At the source, TX[0:9] and TBC switch synchronously with respect to a 125 MHz clock internal to the sender. New data are emitted on both edges of TBC; this is called Double Data Rate (DDR). The HDMP-2634 finds

a sampling window between the two edges of TBC to latch TX[0:9] data into the input register of the transmitter section when  $TX_RATE=1$ . If  $TX_RATE=0$ , the user must ensure no data transitions on the falling edge of TBC and this edge is used to latch in parallel data resulting in a 1.25 GBd serial stream.

The transmitter section's PLL locks to the 125 MHz TBC. This clock is then multiplied by 20 to generate the 2500 MHz serial clock for the high-speed serial outputs. The high-speed outputs are capable of interfacing directly to copper cables or PCB traces for electrical transmission or to a separate fiber optic module for optical transmission. The high-speed outputs include usercontrollable skin-loss equalization to improve performance when driving copper lines.

The receiver section accepts a serial electrical data stream at 1.25 or 2.5 GBd and recovers 10-bit wide parallel data. The receiver PLL locks onto the incoming serial signal and recovers the

# **Features**

- 10-bit wide parallel Tx, Rx busses
- 125 MHz TBC and RBC[0:1]
- Option to set Tx and Rx serial data rates separately
- Parallel data I/O, clocks and control compatible with SSTL\_2
- Differential PECL or LVTTL REFCLK at 125 MHz
- Double data rate transfers
- Source synchronous clocking of transmit data
- Source centered or source synchronous clocking of receive data
- Dual or single receive byte clocks
- Parallel loopback mode
- Differential BLL serial I/O with on-chip source termination
- 14 mm, 64-pin MQFP package
- Single +3.3 V power supply

# **Applications**

- · Gigabit ethernet channel aggregation trunks
- Fast serial backplanes
- Clusters

# **Ordering Information**

**Part Number** Parallel I/0 HDMP-2634 SSTL 2



high-speed incoming clock and data. The serial data is converted back into 10-bit parallel data, optionally recognizing the first seven bits of the K28.5+ comma character to establish byte alignment. If K28.5+ detection is enabled, the receiver section is able to detect comma characters at 1.25 GBd or 2.5 GBd depending on the value of the RX RATE pin.

The recovered parallel data is presented at SSTL\_2 compatible outputs RX[0:9], along with a pair of 125 MHz SSTL\_2 clocks, RBC[0] and RBC[1], that are 180 degrees out of phase from one another and which represent the remote clock. Rising edges of RBC[0] and RBC[1] may be used to latch RX[0:9] data at the destination. Alternatively, both edges of either RBC[1] or RBC[0] may be used to latch Rx data (DDR). The preceding applies when RX\_RATE=1 and RBC\_SYNC=0.

For short distances, there may be a need to have ASICs communicate directly using parallel Tx and Rx lines without the serdes intermediary. To enable this, the Tx and Rx parallel timing schemes must be symmetrical. When RBC\_SYNC=1 and RX\_RATE=1 such symmetry is obtained. In this mode, the RX[0:9] lines switch simultaneously with the rising and falling edges of RBC[1] or RBC[0] just as the TX[0:9] lines switch simultaneously with TBC.

If RX\_RATE=0 and RBC\_SYNC=1 then the RX[0:9] lines switch with the rising edges of RBC[1] just as the TX[0:9] lines switch with the rising edges of TBC. If RBC\_SYNC=0 then RX[0:9] data may be latched on the rising edges of RBC[1] and RBC[0]. In this latter mode, the RBC[0:1] clocks operate at a 62.5 MHz rate.

In summary, by setting RBC SYNC=0 the timing of transmit and receive parallel data with respect to TBC and RBC[0:1] may be arranged so that the upstream protocol device can generate and latch data very simply. This is the source centered mode of operation (case A and C in Table 1, page 8). Alternatively, setting RBC SYNC=1 provides for timing symmetry between Tx and Rx parallel lines at both 1.25 GBd and 2.5 GBd rates. This is the source synchronous mode of opertion (case B and D in Table 1, page 8).

Note when EN\_CDET=1, the first transition of byte 0 of a comma will either coincide with the rising edge of RBC[1] or precede it. This applies regardless of the RX RATE setting.

Table 1 summarizes the behavior of the Rx parallel section under all values of RX\_RATE and RBC\_SYNC. For test purposes, the transceiver provides for on-chip parallel to parallel local loopback functionality controlled through the EWRAP pin. Additionally, the byte alignment feature via detection of the first seven bits of the K28.5+ character may be disabled. This may be useful in proprietary applications which use alternative methods to align the parallel data.

The HDMP-2634 accepts either a differential PECL or a LVTTL reference clock input at 125 MHz.

# **HDMP-2634 Block Diagram**

The HDMP-2634 (Figure 2) is designed to transmit and receive 10-bit wide parallel data over high-speed serial communication lines. The parallel data applied to the transmitter is expected to be encoded per the 8B/10B encoding scheme with special reserved

characters for link management purposes. Other encoding schemes will also work as long as they provide DC balance and a sufficient number of transitions. The HDMP-2634 incorporates the following:

- SSTL 2 Parallel I/O
- High Speed Phase Locked Loops
- Parallel to Serial Converter
- High Speed Serial Clock and Data Recovery Circuitry
- Comma Character Recognition per Fibre Channel Specifications
- Byte Alignment Circuitry
- Serial to Parallel Converter

# **INPUT LATCH**

The transmitter accepts 10-bit wide single ended SSTL 2 parallel data at inputs TX[0:9]. The SSTL 2 TBC clock provided by the sender of the transmit data is used as the transmit byte clock. The TX[0:9] and TBC signals must be properly aligned as shown in Figure 3. If TX RATE=1, TX[0:9] data are latched between both edges of TBC. If TX RATE=0, TX[0:9] data are latched on the falling edge of TBC. The TX[0:9] and TBC inputs are unterminated SSTL 2 inputs per section 4.1 of the SSTL 2 standard (Figure 11).

### TX PLL/CLOCK GENERATOR

The Transmitter Phase Locked Loop and Clock Generator block is responsible for generating all internal clocks needed by the transmitter section to perform its functions. These clocks are based on the supplied transmit byte clock (TBC). Incoming data must be synchronous with TBC (Figures 3a-3b). Use of TBC to determine sampling points to latch data obviates the need for PLLs in the data source.

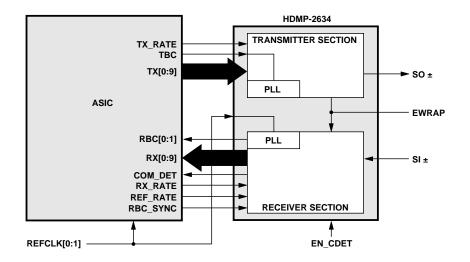


Figure 1. Typical application using HDMP-2634.

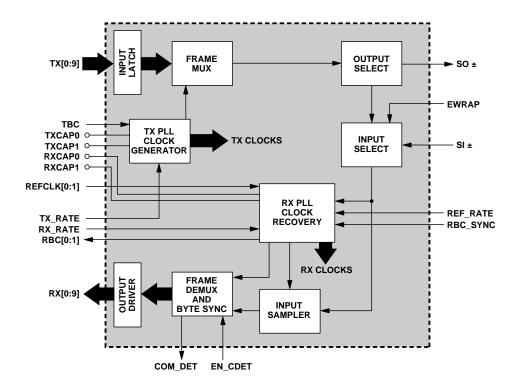


Figure 2. Block diagram of HDMP-2634.

# **FRAME MUX**

The FRAME MUX accepts 10-bit wide parallel data from the INPUT LATCH. Using internally generated high-speed clocks, this parallel data is multiplexed into a 2.5 GBd serial data stream. The data bits are transmitted sequentially from TX[0] to TX[9]. The leftmost bit of K28.5+ is on TX[0].

# **OUTPUT SELECT**

The OUTPUT SELECT block picks the serial data to drive on to the serial output line. In normal operation, the serialized TX[0:9] data is placed at SO±. In parallel loopback (EWRAP=1) mode, the SO± pins are held static at logic 1 and the internal serial output signal going to the INPUT SELECT block of the receiver section is used to generate RX[0:9]. In addition, the **OUTPUT SELECT block allows** the user to control the amount of pre-emphasis used on the SO± pins. If pre-emphasis is used,  $0\rightarrow 1$  and  $1\rightarrow 0$  transitions on SO± have greater amplitude than  $0\rightarrow 0$  and  $1\rightarrow 1$  transitions. This increased amplitude is used to offset the effects of skin loss and dispersion on long PCB transmission lines. Pre-emphasis is controlled by the EQAMP pin (Table 2 and Figure 9).

# **INPUT SELECT**

The INPUT SELECT block picks the serial data that will be parallelized to drive RX[0:9]. In normal operation, serial data is accepted at SI±. In parallel loopback (EWRAP=1) mode, the internal serial output signal from the OUTPUT SELECT block of the transmitter section is used to generate RX[0:9].

# RX PLL/CLOCK RECOVERY

The Receiver Phase Locked Loop and Clock Recovery block is responsible for frequency and phase locking onto the incoming serial data stream and recovering the bit and byte clocks. An automatic locking feature allows the Rx PLL to lock onto the input data stream without external PLL training controls. It does this by continually frequency locking onto the 125 MHz reference clock, and then phase locking onto the selected input data stream. An internal signal detection circuit monitors the presence of the input and invokes the phase detection as the data stream appears. Once bit locked, the receiver generates the highspeed sampling clock for the input sampler.

### **INPUT SAMPLER**

The INPUT SAMPLER is responsible for converting the serial input signal into a retimed bit stream. To accomplish this, it uses the high-speed serial clock generated from the RX PLL/CLOCK RECOVERY block. This serial bit stream is sent to the FRAME DEMUX AND BYTE SYNC block.

# FRAME DEMUX AND BYTE SYNC

The FRAME DEMUX AND BYTE SYNC block is responsible for restoring the 10-bit parallel data from the high-speed serial bit stream. This block is also responsible for recognizing the first seven bits of the K28.5+ positive disparity comma character (0011111xxx). When recognized, the FRAME DEMUX AND BYTE SYNC block works with the RX PLL/CLOCK RECOVERY

block to select the proper parallel data edge out of the bit stream so that the next comma character starts at RX[0]. When a comma character is detected and realignment of the receive byte clock RBC[0:1] is necessary, these clocks are stretched (never slivered) to the next correct alignment position. RBC[0:1] will be aligned by the start of the next ordered set (two-byte group) after K28.5+ is detected. The start of the next ordered set will be aligned with the rising edge of RBC[1], independent of the RX RATE pin setting. Per the Fibre Channel encoding scheme, comma characters must not be transmitted in consecutive bytes so that the receive byte clocks may maintain their proper recovered frequencies.

# **OUTPUT DRIVERS**

The OUTPUT DRIVERS present the 10-bit parallel recovered data (RX[0:9]) properly aligned to the receive byte clock (RBC[0:1]) as shown in Figures 5a-5d and Table 1. These output drivers provide single ended SSTL\_2 compatible signals.

# **RECEIVER LOSS OF SIGNAL**

The RECEIVER LOSS OF SIGNAL block examines the peak-to-peak differential amplitude at the SI± input. When this amplitude is too small, RX\_LOS is set to 1, and RX[0:9] are set to logic one (11111111111). This prevents generation of random data at the RX[0:9] pins when the serial input lines are disconnected. When the signal at SI± is a valid amplitude, RX\_LOS is set to logic 0, and the output of the INPUT SELECT block is passed through.

# SSTL\_2 COMPATIBILITY

The HDMP-2634 works with protocol (FC-1 or MAC) devices whose VDDQ voltage is nominally 2.5 V. Note that the HDMP-2634 works with a single V<sub>CC</sub> supply of 3.3 V. Nonetheless, RX[0:9] and RBC[0:1] generate output voltages that are compatible with section 4.1 of the SSTL 2 standard and are not meant to be terminated in 50  $\Omega$ . In addition, the HDMP-2634 provides a VREFR output pin which may be used at the protocol IC in order to differentially detect a high or a low on RX[0:9]. Alternatively, this voltage may be generated on the PCB using a resistor divider from VDDQ or V<sub>CC</sub> while ignoring the VREFR output of the HDMP-2634. The HDMP-2634 expects SSTL 2 compatible signals at the TX[0:9] and TBC pins. These pins are unterminated per section 4.1 of the SSTL 2 standard (Figure 11). The VREFT input pin is used by the HDMP-2634 to differentially detect a high or low on TBC and TX[0:9]. VREFT may be generated by the protocol device or on the PCB using a resistor divider from VDDQ or  $V_{CC}$ .

# **MULTI-RATE OPERATION**

The HDMP-2630/2631 provide hooks for initializing multi-rate links. A possible algorithm operates as follows. In a point to point link, each node sets its TX\_RATE input pin high to transmit at the highest possible data rate. At the same time, each node tries different values of RX\_RATE to see at which data rate intelligible data is received. Once this data rate is found, TX\_RATE is set to enable this rate. For example, suppose a

node that is capable of operating at 1.25 GBd and 2.5 GBd rates is establishing a link with a node that is capable of only 2.5 GBd. Both nodes will start emitting at 2.5 GBd because this is their highest rate. The first node will try receiving at 1.25 GBd rate. It will not succeed and will therefore try 2.5 GBd reception, which will succeed. The second node is set to 2.5 GBd and has been receiving correct data. These two nodes will settle to 2.5 GBd.

If the second node in the example above operated at 1.25 GBd only, then the first node would see intelligible 1.25 GBd data and set its TX\_RATE=0, at which time the second node would also start seeing intelligible data. These nodes would settle to 1.25 GBd. If both nodes are 1.25/2.5 GBd capable, then they will settle to 2.5 GBd. With this algorithm, nodes need not have a common lowest common denominator data rate to interoperate.

# **HDMP-2634 Transmitter Section Timing Characteristics**

 $T_A = 0$ °C to  $T_C = 85$ °C,  $V_{CC} = 3.15$  V to 3.45 V

Symbol	Parameter	Units	Min.	Тур.	Max.
t <sub>TXCT</sub>	TX[0:9] Input Data and TBC Clock Transition Range (TX_RATE = 1)	ps			1600
t <sub>TXCV</sub>	TX[0:9] Input Data and TBC Clock Valid Time (TX_RATE = 1)	ps	2400		
TXSETUP	TX[0:9] Setup Time to Falling Edge of TBC (TX_RATE = 0)	ps	1400		
t <sub>TXHOLD</sub>	TX[0:9] Hold Time from Falling Edge of TBC (TX_RATE = 0)	ps	1400		
t_txlat <sup>[1]</sup>	Transmitter Latency			0.8 ns +	
				8.5 bits	

# Note:

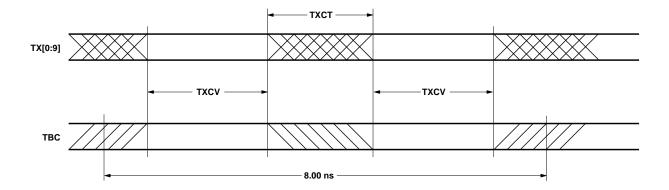


Figure 3a. Parallel transmitter section timing.  $TX_RATE = 1$ .

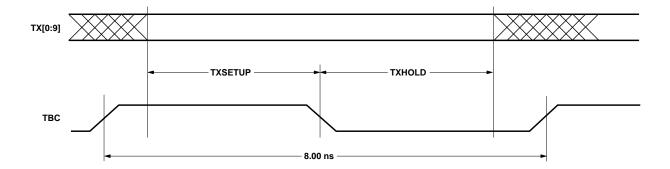


Figure 3b. Parallel transmitter section timing. TX\_RATE = 0.

<sup>1.</sup> The transmitter latency, as shown in Figure 4, is defined as the time between the leading edge of a parallel data word and the leading edge of the first transmitted serial output bit of that data word.

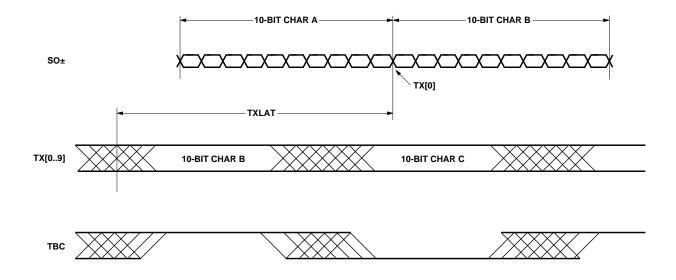


Figure 4. Transmitter latency. TX[0] is first bit on S0 $\pm$ .

# **HDMP-2634 Receiver Section Timing Characteristics**

 $T_A = 0$ °C to  $T_C = 85$ °C,  $V_{CC} = 3.15$  V to 3.45 V

Symbol	Parameter	Units	Min.	Тур.	Max.
f_lock	Frequency Lock at Powerup with REFCLK Active	μs			500
b_sync <sup>[1,2]</sup>	Bit Sync Time	bits		200	2500
t_rxlat <sup>[3]</sup>	Receiver Latency		13.5 bits +2.5 ns		

# Notes:

- 1. This is the recovery time for input phase jumps, per the Fibre Channel Specification X3.230-1994 FC-PH Standard, Sec 5.3.
- 2. Tested using  $C_{PLL}$  = 0.1  $\mu F$ .
- 3. The receiver latency, as shown in Figure 6, is defined as the time between the leading edge of the first received serial bit of a parallel data word and the leading edge of the corresponding parallel output word.

Table 1. HDMP-2634 RX, RBC[0:1] Timing Dependence on RX\_RATE and RBC\_SYNC.

Input	Settings		Resulting Beh	aviors	
Case	RX_RATE	RBC_SYNC	SI Rate (GBd)	RBC Rate (MHz)	Timing Diagrams for RBC0, RBC1, RX[0:9]
Ā	0	0	1.25	62.5	RBC0  RBC1  RX[0:9]
В	0	1	1.25	125	RBC0
С	1	0	2.5	125	RBC0
D	1	1	2.5	125	RBC0

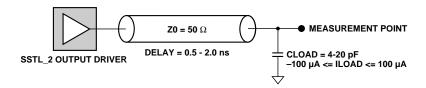


Figure 5. Test conditions for SSTL\_2 output driver.

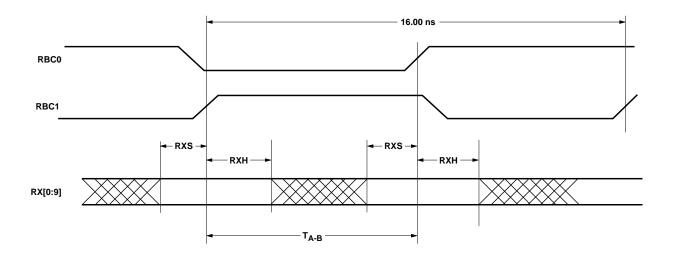


Figure 5a. Receiver section timing – case A.

# Case A of Table 1. (RX\_RATE = 0, RBC\_SYNC = 0) $T_A = 0^{\circ}C$ to $T_C = 85^{\circ}C$ , $V_{CC} = 3.15$ V to 3.45 V

Symbol	Parameter	Units	Min.	Тур.	Max.
t <sub>RXS</sub>	RX[0:9] Setup Time to RBC1 or RBC0 (Data Valid Before)	ps	2700		
t <sub>RXH</sub>	RX[0:9] Hold Time from RBC1 or RBC0 (Data Valid After)	ps	1500		
t <sub>A-B</sub>	RBC1 Rising Edge to RBC0 Rising Edge Skew	ns	7.5		8.5
t <sub>DUTY</sub>	RBC[0:1] Duty Cycle	%	40		60

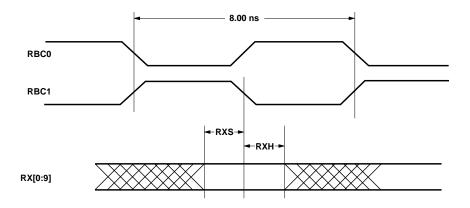


Figure 5b. Receiver section timing – case B.

# Case B of Table 1. (RX\_RATE = 0, RBC\_SYNC = 1)

 $T_A = 0$ °C to  $T_C = 85$ °C,  $V_{CC} = 3.15$  V to 3.45 V

Symbol	Parameter	Units	Min.	Тур.	Max.
t <sub>RXS</sub>	RX[0:9] Setup Time to RBC1 or RBC0 (Data Valid Before)	ps	1500		
t <sub>RXH</sub>	RX[0:9] Hold Time from RBC1 or RBC0 (Data Valid After)	ps	1700		

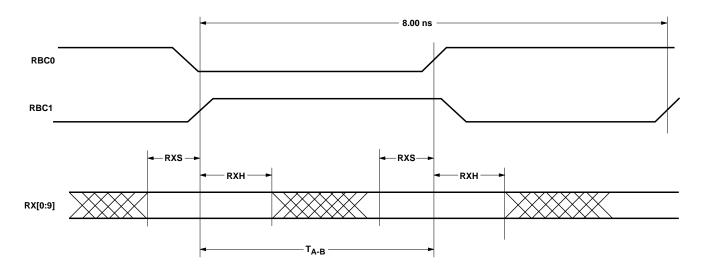


Figure 5c. Receiver section timing - case  $\hbox{\bf C}.$ 

# Case C of Table 1. (RX\_RATE = 1, RBC\_SYNC = 0)

 $T_A = 0^{\circ}C$  to  $T_C = 85^{\circ}C,\,V_{CC} = 3.15$  V to 3.45 V

Symbol	Parameter	Units	Min.	Тур.	Max.
t <sub>RXS</sub>	RX[0:9] Setup Time to RBC1/0 (Data Valid Before)	ps	800		
t <sub>RXH</sub>	RX[0:9] Hold Time from RBC1/0 (Data Valid After)	ps	1000		
t <sub>A-B</sub>	RBC1 Rising Edge to RBC0 Rising Edge Skew	ns	3.8		4.2
t <sub>DUTY</sub>	RBC[0:1] Duty Cycle	%	40		60

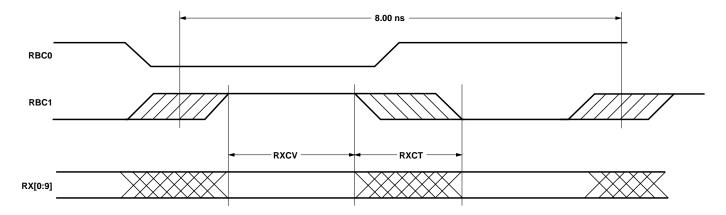


Figure 5d. Receiver section timing – case D.

# Case D of Table 1. (RX\_RATE = 1, RBC\_SYNC = 1)

 $T_A = 0$ °C to  $T_C = 85$ °C,  $V_{CC} = 3.15$  V to 3.45 V

Symbol	Parameter	Units	Min.	Тур.	Max.
t <sub>RXCT</sub>	RX[0:9] Output Data and RBC Clock Transition Range	ps			1500
t <sub>RXCV</sub>	RX[0:9] Output Data and RBC Clock Valid Time	ps	2500		

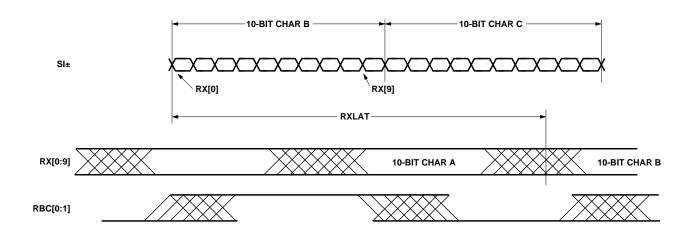


Figure 6. Receiver latency. First bit on SI $\pm$  drives RX[0].

# **HDMP-2634 Absolute Maximum Ratings**

Sustained operation at or beyond any of these conditions may result in long-term reliability degradation or permanent damage, and is not recommended.

Symbol	Parameter	Units	Min.	Max.
$\overline{V_{CC}}$	Supply Voltage	V	-0.5	4.0
T <sub>stg</sub>	Storage Temperature	°C	-65	150
T <sub>C</sub>	Case Temperature	°C	0	95
Tj	Junction Temperature	°C	0	125
V <sub>IN,PECL</sub>	LVPECL Input Voltage	V	-0.5	V <sub>CC</sub> + 0.5 <sup>[1]</sup>
V <sub>IN,SSTL</sub>	SSTL_2 Input Voltage	V	-0.5	V <sub>CC</sub> + 0.5 <sup>[1]</sup>

## Note:

# **HDMP-2634 Guaranteed Operating Rates**

 $T_A = 0^{\circ}C$  to  $T_C = 85^{\circ}C$ ,  $V_{CC} = 3.15 \text{ V}$  to 3.45 V

Parallel Clock Rate (MHz)		Serial Baud Rate (GBd)		Serial Baud Rate (GBd)		
Min.	Max.	Min.	Max.	Min.	Max.	
124	126	1.24	1.26	2.48	2.52	

# **HDMP-2634 Transceiver REFCLK and TBC Requirements**

 $T_A = 0$ °C to  $T_C = 85$ °C,  $V_{CC} = 3.15$  V to 3.45 V

Symbol	Parameter	Units	Min.	Тур.	Max.
f	Nominal Frequency	MHz		125	
F <sub>tol</sub>	Frequency Tolerance	ppm	-100		100
Symm	Symmetry (Duty Cycle)	%	40		60

# **HDMP-2634 DC Electrical Specifications**

 $T_A=0^{\circ}C$  to  $T_C=85^{\circ}C,\,V_{CC}=3.15$  V to 3.45 V

Symbol	Parameter	Units	Min.	Тур.	Max.
I <sub>CC, TRx</sub> [1]	Transceiver Supply Current (total of all supplies)	mA		620	780
P <sub>D, TRx</sub> [1]	Transceiver Total Power Dissipation	mW		2050	2700

### Note

# HDMP-2634 PECL DC Electrical Specifications for REFCLK[0:1]

 $T_A = 0$ °C to  $T_C = 85$ °C,  $V_{CC} = 3.15$  V to 3.45 V

Symbol	Parameter	Units	Min.	Тур.	Max.
V <sub>IH,PECL</sub>	PECL Input High Voltage Level	V	2.10		2.60
V <sub>IL,PECL</sub>	PECL Input Low Voltage Level	V	1.30		1.80

<sup>1.</sup> Must remain less than or equal to absolute maximum  $V_{CC}$  voltage of 4.0 V.

<sup>1.</sup> Measurement Conditions: Tested sending 2.5 GBd 2<sup>7</sup>-1 PRBS sequence from a serial BERT with S0± outputs differentially terminated using a 100 Ω resistor.

# HDMP-2634 LVTTL DC Electrical Specifications for REFCLK[1]

 $T_A = 0^{\circ}C$  to  $T_C = 85^{\circ}C$ ,  $V_{CC} = 3.15$  V to 3.45 V

Symbol	Parameter	Units	Min.	Тур.	Max.
V <sub>IH,LVTTL</sub>	LVTTL Input High Voltage Level	V	2.00		
V <sub>IL,LVTTL</sub>	LVTTL Input Low Voltage Level	V			0.80

# SSTL\_2 I/O Parameters

# **HDMP-2634 Recommended DC Operating Conditions and DC Electrical Characteristics**

 $T_A = 0$ °C to  $T_C = 85$ °C,  $V_{CC} = 3.15$  V to 3.45 V, VDDQ = 2.30 V to 2.70 V. VDDQ is the FC-1/MAC device I/O supply voltage. SSTL\_2 inputs can receive LVTTL signals successfully. SSTL\_2 outputs do not output LVTTL compliant levels.

Symbol	Parameter	Units	Min.	Тур.	Max.
VREFT	SSTL_2 Input Reference Voltage	V	1.15	1.25	1.35
V <sub>IH</sub>	Input High Voltage	V	VREFT +0.35		VDDQ +0.30
V <sub>IL</sub>	Input Low Voltage	V	-0.30		VREFT -0.35
VREFR	SSTL_2 Output Reference Voltage	V	1.15	1.25	1.35
V <sub>OH</sub>	Output High Voltage	V	VREFR +0.38		DDDQ
$V_{0L}$	Output Low Voltage	V	GND		VREFR -0.38

# **HDMP-2634 AC Electrical Specifications**

 $T_A = 0$ °C to  $T_C = 85$ °C,  $V_{CC} = 3.15$  V to 3.45 V

Symbol	Parameter	Units	Min.	Тур.	Max.
t <sub>r,REFCLK</sub>	REFCLK[0:1] PECL Input Rise Time, V <sub>IL,PECL</sub> to V <sub>IH,PECL</sub>	ns			1.5
t <sub>f,REFCLK</sub>	REFCLK[0:1] PECL Input Fall Time, V <sub>IH,PECL</sub> to V <sub>IL,PECL</sub>	ns			1.5
t <sub>rd, HS_OUT</sub>	HS_OUT Differential Rise Time, 20% - 80%	ps		160	
t <sub>fd, HS_OUT</sub>	HS_OUT Differential Fall Time, 20% - 80%	ps		160	
t <sub>r,SSTL</sub>	SSTL Input Rise Time, V <sub>IL,SSTL</sub> to V <sub>IH,SSTL</sub>	ns			1.5
t <sub>f,SSTL</sub>	SSTL Input Fall Time, V <sub>IH,SSTL</sub> to V <sub>IL,SSTL</sub>	ns			1.5
V <sub>IP,HS_IN</sub>	HS_IN Input Peak-To-Peak Differential Voltage	mV	200		2000
V <sub>OP,HS_OUT</sub> [1]	HS_OUT Output Pk-Pk Diff. Voltage (Z0 = 50 $\Omega$ , Fig. 9)	mV	800	1050	2000
V <sub>OP,HS_OUT</sub> <sup>[1]</sup>	HS_OUT Output Pk-Pk Diff. Voltage (Z0 = 75 $\Omega$ , Fig. 9)	mV	1100	1400	2000

### Note:

<sup>1.</sup> Output Differential Voltage defined as (S0+ - S0-). Measurement made with Tx pre-emphasis off (EQAMP tied to  $V_{CC}$  with a 100  $\Omega$  resistor).

# **HDMP-2634 Transmitter Section Output Jitter Characteristics**

 $T_A = 0$ °C to  $T_C = 85$ °C,  $V_{CC} = 3.15$  V to 3.45 V

Symbol	Parameter	Units	Тур.
RJ <sup>[1]</sup>	Random Jitter at S0 $\pm$ (1 $\sigma$ deviation of the 50% crossing point)	ps	6.2
DJ <sup>[2]</sup>	Deterministic Jitter at SO± (peak-to-peak), K28.5+/K28.5- Pattern	ps	22
DJ	Deterministic Jitter at SO± (peak-to-peak), CRPAT <sup>[3]</sup> Pattern	ps	31

# Notes:

- 1. Defined by Fibre Channel Specification X3.230-1994 FC-PH, Annex A, Section A.4.4 (oscilloscope method) and tested using the setup shown in Figure 8b.
- 2. Defined by Fibre Channel Specification X3.230-1994 FC-PH, Annex A, Section A.4.3 and tested using the setup shown in Figure 8a.
- 3. Defined in the Fibre Channel Technical Report "Methodologies for Jitter Specification," Annex B, and tested using the setup shown in Figure 8a.

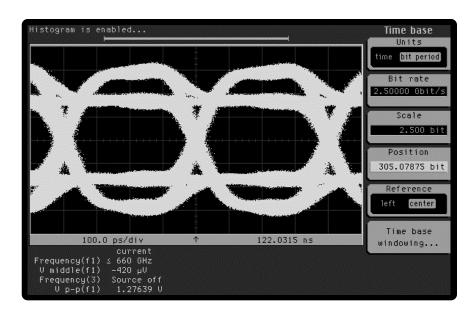


Figure 7a. Serial output eye diagram with nominal Tx pre-emphasis.

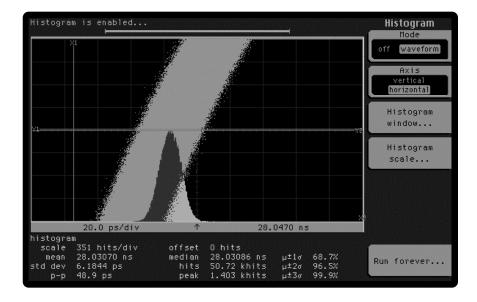


Figure 7b. Serial output random jitter with Tx pre-emphasis off.

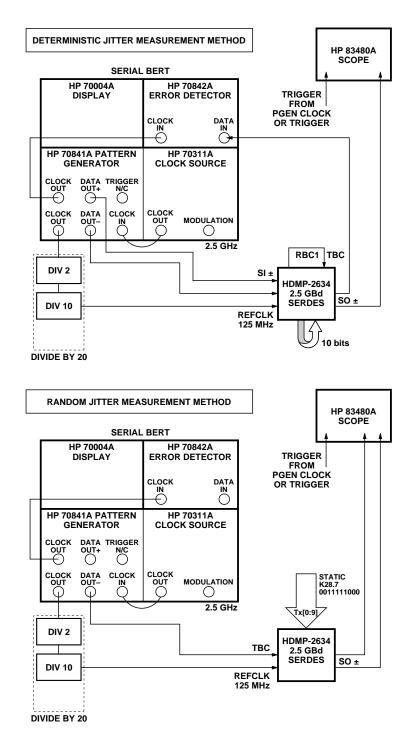


Figure 8a-b. Transmitter deterministic and random jitter measurement method.

# **HDMP-2634 Thermal Characteristics**

 $T_A = 0$ °C to  $T_C = 85$ °C,  $V_{CC} = 3.15$  V to 3.45 V

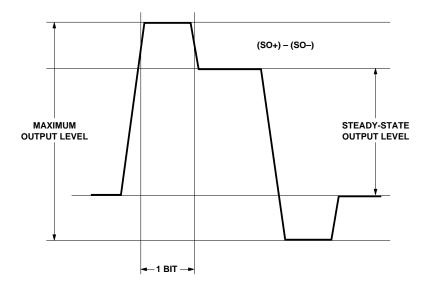
Symbol	Parameter	Units	Тур.
$\Theta_{jc}^{[1]}$	Thermal Resistance, Junction to Case	°C/W	9.3

# Note:

<sup>1.</sup> Based on independent package testing by Agilent.  $\Theta_{ja}$  for these devices is 38°C/W for the HDMP-2634.  $\Theta_{ja}$  is measured on a standard 3x3" FR4 PCB in a still air environment. To determine the actual junction temperature in a given application, use the following equation: Tj = Tc + ( $\Theta_{jc}$  x P<sub>D</sub>), where Tc is the case temperature measured on the top center of the package and P<sub>D</sub> is the power being dissipated.

# **HDMP-2634 Pin Input Capacitance**

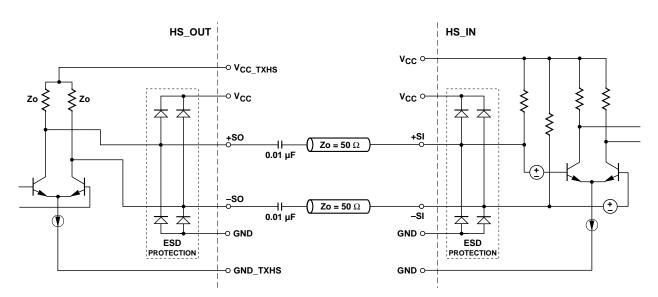
Symbol	Parameter	Units	Тур.
CINPUT	Input Capacitance on SSTL input pins	pF	1.6



STEADY-STATE OUTPUT LEVEL	MAXIMUM OUTPUT LEVEL	EQAMP SETTING
1.11 V	1.11 V	100 $\Omega$ to V <sub>CC</sub> (NO PRE-EMPHASIS)
820 mV	1.28 V	FLOATING (NOMINAL PRE-EMPHASIS)
570 mV	1.44 V	SHORTED TO GND (MAXIMUM PRE-EMPHASIS)

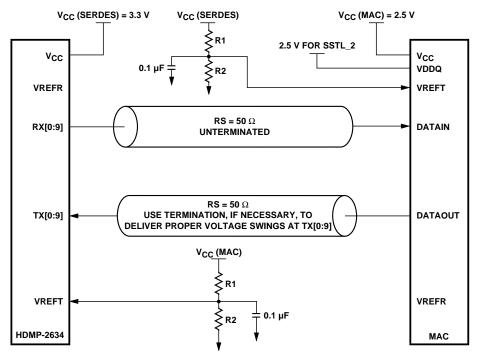
ALL VALUES MEASURED IN A 50  $\Omega$  ENVIRONMENT WITH VCC = 3.3 V AND TA = 25°C.

Figure 9. Tx pre-emphasis control using EQAMP pin.



NOTE: HS\_IN INPUTS SHOULD NEVER BE CONNECTED TO GROUND AS PERMANENT DAMAGE TO THE DEVICE MAY RESULT. Z0 = 75  $\Omega$  May also be used.

Figure 10. HS\_OUT and HS\_IN simplified circuit schematic for HDMP-2634.



NOTE: VREFR ON EACH DEVICE MAY BE USED TO DRIVE VREFT ON THE OTHER DEVICE INSTEAD OF USING THE CONFIGURATION ABOVE. VREFR SHOULD BE BYPASSED WITH 0.1  $\mu\text{F}$  IN THIS CASE. IF USED, R1 + R2 SHOULD BE 500-1000  $\Omega$ . 1% RESISTORS SHOULD BE USED FOR R1 AND R2. WHEN USING THE CONFIGURATION ABOVE, VREFT TO THE MAC DEVICE SHOULD BE SET TO 1.25 V NOMINAL. USING THIS VALUE CENTERS VREFR RELATIVE TO THE RX[0:9] OUTPUT SWINGS PROVIDED BY THE HDMP-2634.

Figure 11. I-SSTL2 and O-SSTL2 simplified circuit schematic.

# I/O Type Definitions

I-SSTL2 Input SSTL_2. These inputs will receive LV 0-SSTL2 Output SSTL_2. These outputs will not pro	TTL-compliant signals successfully.
0-SSTL2 Output SSTL_2. These outputs will not pro	
	duce LVTTL-compliant signals.
HS_OUT High Speed Output, ECL Compatible	
HS_IN High Speed Input	
C External Circuit Node	
S Power Supply or Ground	

Table 2. Pin Definitions for HDMP-2634

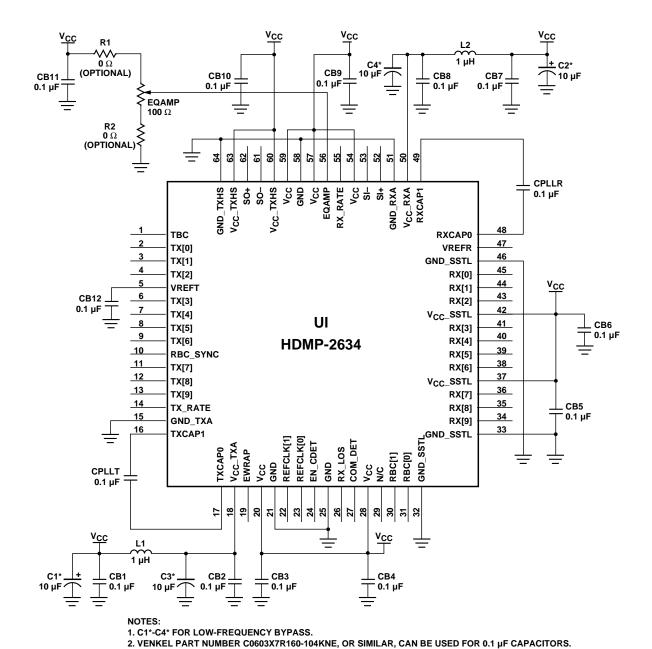
Name	Pin	Type	Signal	
EQAMP	56	С	Output Equalization Amplitude Control: Controls the relative amount of equalization on the high-speed serial data outputs. Equalization is disabled by connecting a 100 $\Omega$ resistor from EQAMP to V <sub>CC</sub> . The amount of equalization can be increased by either increasing the value (above 100 $\Omega$ ) of a resistor connected from EQAMP to V <sub>CC</sub> , or decreasing the value of a resistor connected from EQAMP to GND. Maximum equalization is obtained by connecting EQAMP directly to GND. See Figure 9.	
EWRAP	19	I-SSTL2	<b>Loop Enable:</b> When high, the high speed serial output data is internally connected directly to the receiver circuit, bypassing the high-speed input and output buffers. The external high-speed data outputs S0± are set high and SI± inputs are ignored.	
EN_CDET	24	I-SSTL2	Comma Detect Enable: When high, enables detection of comma character.	
COM_DET	27	0-SSTL2	Comma Detect Indicator: When high, indicates that a comma character of positive disparity (0011111xxx) has been detected on the high speed serial input line.	
TX_RATE	14	I-SSTL2	<b>Transmit Rate Set:</b> If set to low, the HDMP-2634 reads TX[0:9] data on the falling edge of TBC and serializes it. This corresponds to a 1.25 GBd serial stream. If set to high, the HDMP-2634 reads TX[0:9] data between both edges of TBC and serializes it. This corresponds to a 2.5 GBd serial stream.	
RX_RATE	55	I-SSTL2	Receive Rate Set: If set to low, the HDMP-2634 samples the incoming serial stream at 1.25 GBd and drives it on the RX[0:9] lines with the rising edge of RBC1. If set to high, the HDMP-2634 samples the incoming serial stream at 2.5 GBd and drives it on the RX[0:9] lines with the rising edges of RBC1 and RBC0. (Table 1.)	
RBC_SYNC	10	I-SSTL2	<b>Receive Byte Clock Synchronization Control:</b> When RBC_SYNC=1, RX[0:9] data has the same relation to RBC[0:1] as TX[0:9] data has to TBC. ASICs designed using this mode have the option of avoiding a SERDES driven serial link and communicating directly on parallel lines, for short distances.	
RX_LOS	26	0-SSTL2	<b>Loss of Signal at the Receiver Detect:</b> Indicates a loss of signal on the high-speed differential inputs, SI $\pm$ , as in the case where the transmission cable becomes disconnected. If SI $\pm$ >= 200 mV peak-to-peak differential, RX_LOS = logic 0. If SI $\pm$ < 200 mV and SI $\pm$ > 75 mV, RX_LOS = undefined. If SI $\pm$ =< 75 mV, RX_LOS = logic 1, RX[0:9]=1111111111.	
S0+ S0-	62 61	HS_OUT	<b>Serial Data Outputs</b> : High speed outputs. These lines are active when not in parallel loop mode (EWRAP=0). When EWRAP is high, these outputs are held static at logic 1.	
SI+ SI-	52 53	HS_IN	<b>Serial Data Inputs:</b> High speed inputs. Serial data is accepted from SI $\pm$ inputs when EWRAP is low.	
TBC	01	I-SSTL2	<b>Transmit Clock:</b> Both edges of this input are used to determine the sampling window for transmit parallel data. The transmitter section accepts this signal as the frequency reference clock. It is multiplied by 20 to generate the outgoing serial bit clock and other internal clocks.	
RBC[1] RBC[0]	30 31	0-SSTL2	Receive Byte Clocks: The receiver section recovers two receive byte clocks. These two clocks are 180 degrees out of phase. See Table 1 for timing relationships.	
REFCLK[1]	22	I-PECL or I-LVTTL	Reference Clock: A 125 MHz clock supplied by the host system. It serves as the reference clock for the receive portion of the transceiver. These pins may be driven by a differential PECL clock source or a single ended LVTTL clock source. In the LVTTL case, REFCLK[1] is to be driven and REFCLK[0] is to be bypassed to GND via a	
REFCLK[0]	23	I-PECL	0.1 μF capacitor.	

Table 2. Pin Definitions for HDMP-2634, continued

Name	Pin	Type	Signal
TX[0]	02	I-SSTL2	<b>Data Inputs:</b> One 10-bit, encoded character to the $S0\pm$ serial outputs. TX[0] is the first
TX[1]	03		bit transmitted. TX[0] is the least significant bit.
TX[2]	04		•
TX[3]	06		
TX[4]	07		
TX[5]	80		
TX[6]	09		
TX[7]	11		
TX[8]	12		
TX[9]	13		
RX[0]	45	0-SSTL2	Data Outputs: One 10-bit encoded character from one of the SI± serial inputs. RX[0] is
RX[1]	44	0 00112	the first bit received. When RX_LOS =1, there is a loss of input signal at SI±, and these
RX[2]	43		outputs are held static at logic 1. Refer to RX_LOS pin definition for more details.
RX[3]	41		outputs are note state at rogic in motor to the 200 pin dominator for motor dotails.
RX[4]	40		
RX[5]	39		
RX[6]	38		
RX[7]	36		
RX[8]	35		
RX[9]	34		
TXCAP0	17	С	Loop Filter Capacitor: A loop filter capacitor for the internal transmit PLL must be
TXCAPI	16	C	connected across the TXCAP0 and TXCAP1 pins. (typical value is $0.1 \mu F$ )
RXCAP0	48	С	Loop Filter Capacitor: A loop filter capacitor for the internal receive PLL must be
RXCAP1	49		connected across the RXCAPO and RXCAP1 pins. (typical value is 0.1 µF)
V <sub>CC</sub>	20	S	Logic Power Supply: Normally 3.3 volts. Used for internal PECL logic.
<b>V</b> 66	28	O	Logio i ovoi ouppiy. Wormany olo voito. Obod for internal i Loc logio.
	57		
	59		
	54		
V <sub>CC</sub> _TXA	18	S	<b>Analog Power Supply</b> : Normally 3.3 volts. Used to provide a clean supply line for transmit PLL and high speed analog cells.
V <sub>CC</sub> _RXA	50	S	Analog Power Supply: Normally 3.3 volts. Used to provide a clean supply line for
			receive PLL and high speed analog cells.
V <sub>CC</sub> _TXHS	60	S	High Speed Supply: Normally 3.3 volts. Used only for the high speed transmit cell
-	63		(HS_OUT). Noise on this line should be minimized for best operation.
VREFT	05	S	Voltage Reference Input: Used with I-SSTL2 inputs to the HDMP-2634. (Figure 11.)
VREFR	47	S	Voltage Reference Output: Used with 0-SSTL2 outputs from the HDMP-2634. (Figure 11.)
V <sub>CC</sub> _SSTL	37	S	SSTL I/O Supply Voltage for SSTL_2. Normally 3.3 V. All necessary voltages for
V((_331L	42	3	SSTL_2 operation are internally generated.
			_ · · · · · · · · · · · · · · · · · · ·
GND	21	S	<b>Logic Ground:</b> Normally 0 volts. This ground is used for internal PECL logic.
	25		
	58		
GND_TXA	15	S	<b>Analog Ground:</b> Normally 0 volts. Used to provide a clean ground plane for the PLL and high-speed analog cells.
GND_RXA	51	S	Analog Ground: Normally 0 volts. Used to provide a clean ground plane for the receiver PLL and high-speed analog cells.

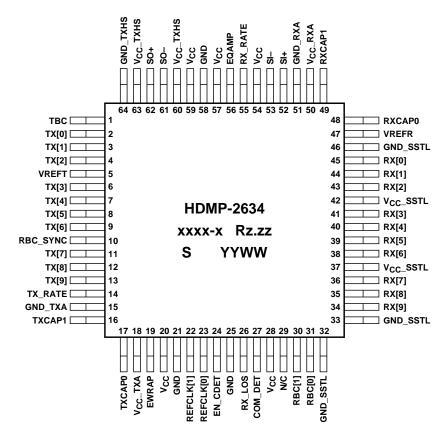
Table 2. Pin Definitions for HDMP-2634, continued

Name	Pin	Туре	Signal
GND_TXHS	64	S	High Speed Ground: Normally 0 volts. Used for HS_IN cell.
GND_SSTL	32 33 46	S	SSTL Ground: Normally 0 volts. Used for SSTL_2 I/O.
N/C	29		<b>No Connect.</b> Any voltage between GND and $V_{\text{CC}}$ may be applied to this pin.



3. TDK P/N NL322522T-1R0J, OR SIMILAR, CAN BE USED FOR 1  $\mu\text{H}$  INDUCTORS.

Figure 12. Recommended power supply filtering arrangement.



XXXX-X = WAFER LOT NUMBER-BUILD NUMBER
RZ.ZZ = DIE REVISION
S = SUPPLIER CODE
YYWW = DATE CODE (YY = YEAR, WW = WORK WEEK)
COUNTRY = COUNTRY OF MANUFACTURE
(MARKED ON BACK OF DEVICE)

Figure 13. HDMP-2634 package layout and marking, top view.

# **Package Information**

Item	Details
Package Material	Metric Metal QFP
Lead Finish Material	85% Tin, 15% Lead
Lead Finish Thickness	200-800 micro-inches
Lead Skew	0.20 mm max.
Lead Coplanarity (Seating Plane Method)	0.08 mm max.

# **Mechanical Dimensions of HDMP-2634**

